Event Date: July-August 2020 (tentative)

Nikkei Electronics Seminar

Vehicle-mounted Imaging Solutions 2020
The latest trends in the development of cameras, LiDAR, millimeter-wave radars and next-generation sensors and the future of vehicle-mounted high-speed interface (tentative theme)

Sponsorship Invitation
The tempo of the development of solutions indispensable for object-recognition of vehicle surroundings, the core of self-driving car technology, is gathering speed. Those companies and institutes that are actively developing the three particular types of sensors — cameras, LiDAR (light detection and ranging, laser imaging detection and ranging) and millimeter-wave radars — for 3D recognition of areas surrounding vehicles are constantly coming up new technological proposals — which are not a mere extension of the conventional solutions. First-generation solutions for autonomous vehicles are likely to be an advanced version of the three types with enhanced performance. The development of next-generation sensing solutions is progressing in an innovative and discontinuous way even though they are inheriting the best and most excellent parts of the existing solutions. As such, there is a possibility that even the current approach to sensor technology fusion will end up drastically changing.

As sensing technology advances, attention is being paid to efforts that are gathering pace to further advance vehicle-mounted high-speed interfaces to be applied to high resolution image data for advanced driver assistance systems (ADAS) as well as LiDAR and radar vehicle systems.

This seminar will be a one-stop knowledge shop as we plan to give an omnibus introduction of all the newest sensor technologies and focus on the latest moves with regard to vehicle-mounted high-speed interfaces. It will also serve as a venue to develop new relationships with lecturers.

It must be a perfect opportunity to strengthen your company’s presence by giving a presentation as a sponsor and by exchanging business cards with seminar participants. The seminar will attract executive officers as well as managers and engineers responsible for corporate planning, R&D, design and product planning at electronic and electric equipment manufacturers, automakers and automobile component manufacturers, among others. We would like your company to give consideration to becoming a sponsor of the seminar.
| Title | Vehicle-mounted Imaging Solutions 2020  
The latest trends in the development of cameras, LiDAR, millimeter-wave radars and next-generation sensors and the future of vehicle-mounted high-speed interface (*tentative theme*) |
<table>
<thead>
<tr>
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<tbody>
<tr>
<td>Organizer</td>
<td>Nikkei Electronics</td>
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<tr>
<td>Venue</td>
<td>To be announced (TBA) (We plan to use a conference room in Tokyo)</td>
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<tr>
<td>Date &amp; time</td>
<td>TBA (We tentatively plan to hold the seminar sometime in mid-September); 10:00-17:00 (lunch available)</td>
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<tr>
<td>Attendance fee</td>
<td>JPY 69,800 (including tax)</td>
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<tr>
<td>Number of attendees</td>
<td>100 people</td>
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<tr>
<td>Expected attendees</td>
<td>Engineers and managers responsible for R&amp;D, design and product planning as well as corporate planning managers and executive officers at electronic and electric equipment manufacturers, automakers and automobile component manufacturers, among others</td>
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</tbody>
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※ This is tentative and may be subject to change.
Seminar Program (tentative) & Previous Seminar’s Program (for reference only)

※Program (tentative)
(We currently intends to choose lecturers from a list of experts in the relevant fields who have so far interviewed by Nikkei Automotive. This may be subject to change.)

- Organizer’s opening remarks
- Overseas sensor maker
- Japanese supplier
- Service vendor using leading-edge sensors
- Government representative

※Omnibus introduction of newest sensor technologies

- Lectures by sponsoring companies
- Panel discussion
  “The latest trends in next-generation sensors” (tentative theme)
- Networking

2019 Program

All you need to know about LiDAR: From rotating type to solid-state type
Mr. Rick Tewell
COO
Velodyne Lidar (US)

Solid-state LiDAR for vehicles
Mr. Omer Keilaf
Founder and CEO
Innoviz Technologies (Israel)

Millimeter-wave radar as an alternative to LiDAR for all-round obstacle detection; software for high spatial resolution
Mr. Yoshihisa Amano
ADAS Development Section Chief, Development Headquarters, U-Shin

3D emulation of human cognition processes; improving machine’s recognition capability with use of 3D camera
Ms. Maiko Asada
Representative Director/President. Revatron

Advanced radar for driverless cars
Dr. Maha Achour
Founder and CEO
Metawave (US)

A single-chip digital approach to MIMO Radars
Dr. Vito Giannini
Senior Design Manager
Uhnder (US)

Bringing the power of radar to autonomous driving
Mr. Bert Francis
Senior Director, Product
Arbe Robotics (Israel)
Seminar Attendee Profile (for reference only)

※Companies:

Aisin Seiki  
Active Imaging  
Analog Devices  
Alps Alpine  
Omron  
Canon  
Crestec  
Koito Electric Industries  
Continental Automotive  
Sick  
3M Japan  
Sense Time Japan  
Socionext  
Sony  
Sony Semiconductor Solutions  
Tamron  
Tower Semiconductor Japan  
Denso  
Topcon  
Nifco  
Nippon Pillar Packing  
NEXTY Electronics  
Panasonic  
Volkswagen Group Japan  
Honda Motor  
Micro Technology  
Mitsumi Electric  
Morpho  
U-Shin  
Ricoh

Asahi Kasei Electronics  
Okamoto Glass  
Furukawa Electric  
University of Tokyo  
Mitsubishi Chemical  
Mitsubishi Heavy Industries  
Mitsubishi Electric  
Mitsubishi Electric/Himeji Works  
Sumitomo Corporation  
Sumitomo Precision Products  
Sumitomo Electric  
Suruga Production Platform  
Koito Manufacturing  
Murata Machinery  
Murata Manufacturing  
Tanaka Kikinzoku Kogyo  
Toray  
Toshiba  
Toshiba Device & Storage  
TOYO Corporation  
National Agency for Automobile and Land Transport Technology (NALTEC)  
NGK Insulators  
NIDEC Mobility  
NGK Spark Plug  
Hitachi Automotive Systems  
Hitachi Construction Machinery  
Hamamatsu Photonics  
Fujitsu Advanced Engineering  
Honda R&D  
Yazaki Components

Yano Research Institute  
Amsterdam Molecular Therapeutics (Netherlands)  
Fuji Electric Corp. of America  
JSR  
NEC Solution Innovator  
OKI  
OTSL  
Steravision
Seminar Attendee Profile (for reference only)

※Occupation
- Research and Development: 17%
- Technology / Design: 13%
- Marketing: 16%
- Management / Executive: 51%

※Industry
- Electronics / Electronic Equipment: 48%
- Automotive: 22%
- Other manufacturing: 13%
- Others: 17%

※Position
- Management / Executive: 54%
- Manager: 23%
- Manager: 8%
- Chief: 8%
- Others: 7%
Sponsorship Menu

Sponsorship Plan A (for up to 2 companies)
<Presentation/review>

- Length of sponsor presentation: 30 minutes
- Publication of an advertorial on the sponsor’s presentation: Nikkei Electronics, December 2020 issue (on sale Nov. 20)
- Participation in the networking event
- Use of the catalog corner: Up to 2 items for free distribution)

※Up to 2 people — a panelist and another person — from your company can attend the seminar without paying any attendance fee.

Merits of sponsorship:
Through its lecture, the sponsoring company is able to strengthen its presence by making it and its solutions better known among seminar attendees and Nikkei Electronics subscribers.

Sponsorship fee

JPY 1,980,000
(Tax included)
Sponsorship Menu

Sponsorship Plan B (for up to 2 companies)
<Panel discussion>

☐ Participation in the panel discussion as a panelist

☐ The sponsoring company will become entitled to run a 1 4-color ad page in the December 2020 issue of the Nikkei Electronics (on sale Nov. 20).

☐ Participation in the networking event

☐ Use of the catalog corner: Up to 2 items for free distribution)

※ Up to 2 people — a panelist and another person — from your company can attend the seminar without paying any attendance fee.

Sponsorship fee
JPY 1,430,000
(Tax included)

Merits of sponsorship:
Through panel discussion participation, the sponsoring company is able to strengthen its presence by making it and its solutions better known among the panel discussion audience and Nikkei Electronics subscribers.
Application deadline: Mid-July 2020 (tentative)

Moreover, we can offer, upon request, customized Nikkei xTECH and Nikkei Automotive menus in addition to the sponsorship menu shown above. Please contact us for further information.